



LCD MODULE

MODULE NO.:

KSET03507N-A40

Customer:							
Approved by:							
Checked by	Prepared by						
	Checked by						

RECORDS OF REVISION

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1. General Specifications

	Feature	Spec
	Size	3.5 inch
	Resolution	320(RGB) x 480
	Interface	RGB 24 bits
Dienley Spee	Technology type	a-si TFT
Display Spec	Pixel pitch(mm)	0.153 x 0.153
	Display colors	262K
	TFT Driver IC:	ILI9488
	Viewing Direction	IPS
	LCM(W x H x D)(mm)	54.66 x 82.94 x 2.20(MAX)
Mechanical	Active Area(mm)	48.96 x 73.44
Characteristics	Weight (g)	TBD
	LED Numbers	6 LEDS

Note 1: Viewing direction for best image quality is different from TFT definition; there is a 180 degree shift.

Note 2: Requirements on Environmental Protection: RoHS.

Note 3: LCM weight tolerance:+/-5%.

2. Input/Output Terminals

No.	Symbol	Description	
1	XR		
2	YU	T 1 D .	
3	XL	Touch Pane pin	
4	YD		
5	GND	System Ground	
6	VCC	Analog power supply	
7	VCC	Analog power supply	
8	FMARK	Frame head pulse	
9	CS	Chip select input pin	
10	RS	Data/Instruction selection pin	
11	WR/SCL	Write control pin	
12	RD	Read control pin	
13	SDI	Serial data input pin and used for the DBI type C mode.	
14	SDO	Serial data input pin and used for the DBI type C mode.	
15	RESET	This signal reset pin	
16	GND	System Ground	
17-32	DB0-DB15	Data Bus	
33	LED-A	Backlight LED Anode.	
34	LED-K1	Backlight LED cathode	
35	LED-K2	Backlight LED cathode	
36	LED-K3	Backlight LED cathode	
37	GND	System Ground	
38	IM0		
39	IM1	Interface Mode Select	
40	IM2		

3. Absolute Maximum Ratings

Item	Symbol	MIN	MAX	Unit	Remark
Supply Voltage	V_{CI}	-0.3	+4.6	V	2
Supply voltage	IOVCC	-0.3	+4.6	V	1
Operating Temperature	T_{OPR}	-20	70	$^{\circ}$	
Storage Temperature	T_{STG}	-30	80	$^{\circ}$	

Notes:

- 1. Make sure IOVCC \geq GND
- 2. Make sure $VCI \ge GND$.

4. Electrical Characteristics

4.1 Driving TFT LCD Panel

 $Ta = 25 \, ^{\circ}C$

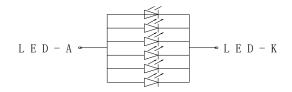
Item	Symbol	MIN	TYP	MAX	Unit	Remark
Digital Supply Voltage	IOVCC	1.65	2.8	3.3	V	
Analog Supply Voltage	VCI	2.5	2.8	3.3	V	
Logic High level input voltage	$V_{ m IH}$	0.7*IOVCC	ı	IOVCC	V	
Logic Low level input voltage	$ m V_{IL}$	0	1	0.3* IOVCC	V	
Logic High level Output voltage	$ m V_{IH}$	0.7*IOVCC	1	IOVCC	V	
Logic Low level Output voltage	$ m V_{IL}$	0		0.2* IOVCC	V	

4.2. Driving Backlight

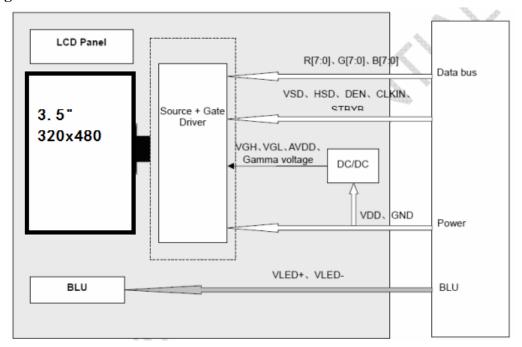
 $Ta = 25 \, ^{\circ}C$

Item	Symbol	MIN	TYP	MAX	Unit	Condition
Forward Current	$ m I_F$	-	90	120	mA	
Forward Voltage	V_{F}	2.8	3.0	3.2	V	IF=15*6mA
Backlight Power consumption	$W_{ m BL}$	-		480	mW	
Luminance for LCM	-	280			Cd/m ²	

Note: 1. the figure below shows the connection of backlight LED.

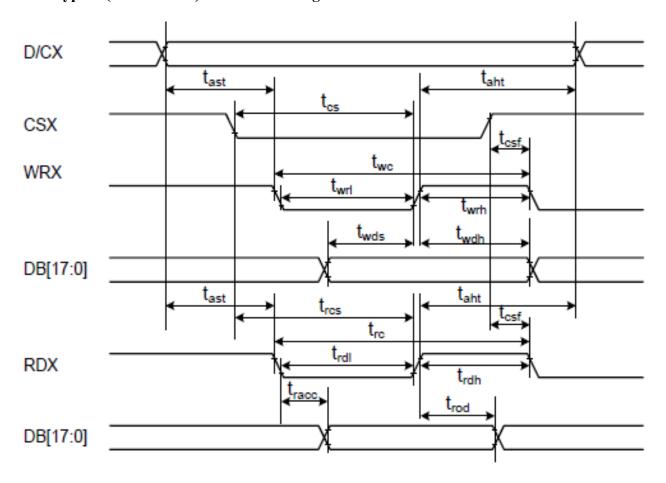


4.3 Block Diagram



5. Timing Chart

5.1 DBI Type B (18/16/9/8 bit) Interface Timing Characteristics

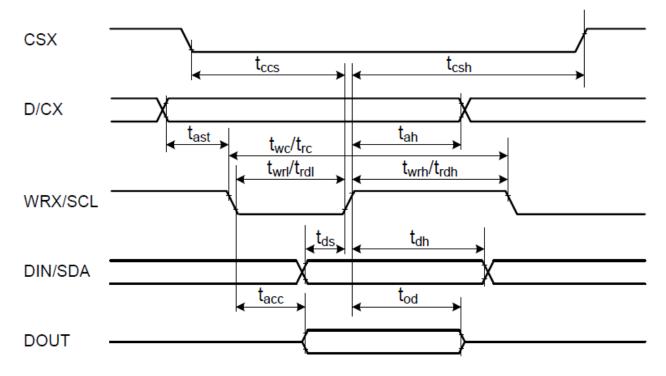


Signal	Symbo I	Parameter	min	max	Unit	Description
DICY	tast	Address setup time	10	-	ns	
D/CX	taht	Address hold time (Write/Read)	10	-	ns	
	tes	Chip Select setup time (Write)	20	-	ns	
CSX	tres	Chip Select setup time (Read)	20	-	ns	
	tesf	Chip Select Wait time (Write/Read)	20	-	ns	
	twc	Write cycle	100	-	ns	
WRX	twrh	Write Control pulse H duration	30	-	ns	
	twrl	Write Control pulse L duration	20	-	ns	
	tre	Read cycle	450	-	ns	
RDX	trdh	Read Control pulse H duration	250	-	ns	
	trdl	Read Control pulse L duration	170	-	ns	
DB[17:0],	twds	Write data setup time	15	-	ns	
DB[15:0],	twdh	Write data hold time	25	-	ns	For maximum CL=30pF
DB[8:0],	tracc	Read access time	10	340	ns	For minimum CL=8pF
DB[7:0]	trod	Read output disable time	10	-	ns	

Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Note: Ta = -30 to 70 °C, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, GND=0V

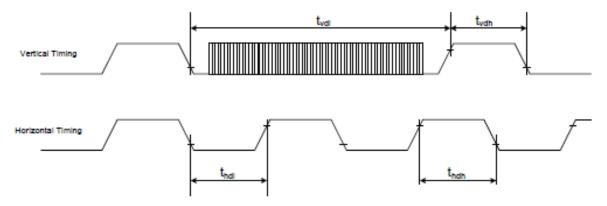
5.2 DBI Type C Interface Timing Characteristics



Signal	Symbol	Parameter	Min.	Max.	Unit	Description
CSX	t _{css}	Chip select setup time (Write)	40	-	ns	
CSA	t _{csh}	Chip select hold time (Write)	40	-	ns	
D/CX	t _{as}	Address setup time	10		ns	
D/CX	t _{ah}	Address hold time (Write/Read)	10		ns	
WDW O	t _{we}	Write cycle	100		ns	
WRX/SCL (Write)	t _{wrh}	SCL High duration (write)	40		ns	
(vviite)	t _{wrl}	SCL Low duration (write)	40		ns	
WDWOOL	t _{re}	Read cycle	300		ns	
WRX/SCL (Read)	t _{rdh}	SCL High duration (read)	120		ns	
(Read)	t _{rdl}	SCL Low duration (read)	120		ns	
DIN/SDA	t _{ds}	Data setup time	30		ns	
(Driver IC)	t _{dh}	Data hold time	30		ns	
DOUT	tacc	Access time	-	110	ns	
(Driver IC)	t _{od}	Output disable time	10		ns	

5.3 Tearing Effect Line Timings

The tearing effect signal is described below:



AC characteristics of Tearing Effect Signal (Frame Rate = 60.5Hz)

Symbol	Parameter	Min.	Max.	Unit	Description
t _{vdl}	Vertical timing low duration	TBD		ms	
t _{vdh}	Vertical timing high duration	TBD		us	
t _{hdl}	Horizontal timing low duration	TBD		us	
t _{hdh}	Horizontal timing high duration	TBD		us	

Notes:

- 1. The timings in Table 8.3.1 apply when MADCTL B4=0 and B4=1
- 2. The signal's rise and fall times (tf, tr) are stipulated to be equal to or less than 15ns.



The Tearing Effect Output Line is fed back to the MCU and should be used as shown below to avoid Tearing Effect:

The Tearing Effect output line supplies to the MCU a Panel synchronization signal. This signal can be enabled or disabled by the set_tear_off(34h), set_tear_on(35h) commands. The mode of the Tearing Effect Signal is defined by the Parameter of the Tearing Effect Line On command. The signal can be used by the MCU to synchronize Frame Memory Writing when displaying video images.

TEON (35h)	TELOM (35h, 1 st bit)	TE signal Output
0	*	GND
1	0	TE (Mode 1)
1	1	TE (Mode 2)

6. Optical Characteristics

Optical specifications

Items		Symbol	Condition	Specifications			Unit	Domayle
				Min.	Typ.	Max.	Unit	Remark
Contrast Ratio		CR	$\theta = 0$	300	400	-	-	
Response Time		T_R	25℃	-	20	30	ms	
		T_{F}		-	20	30	ms	
	Red	X_R		0.611	0.613	0.615	-	Note
Chromatics		Y_R		0.333	0.335	0.337	-	
	Green	X_{G}		0.305	0.307	0.309	-	
		Y_{G}		0.558	0.560	0.562	-	
	Blue	X_{B}		0.133	0.135	0.137	-	
		${ m Y_B}$		0.158	0.160	0.162	-	
	White	X_{W}		0.324	0.326	0.328	-	
		Y_{W}		0.364	0.366	0.368	-	
Viewing angle	Hor.	φR(3 o'clock)	Center CR≥10	70	80	-	deg.	
		φL(9 o'clock)		70	80	ı		
	Ver.	θU(12 o'clock)		70	80	1		
		θD(6 o'clock)		70	80	-		
Uniformity		U		75	80			
NTSC ratio					50		%	
Luminance		Lv		280			cd/m ²	
Hardness					3H			
Operating life time			I_{BL} =90mA	-	50000		h	

Note 1: Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63

L0: Luminance of gray level 0

CR = CR (10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note 5.

Note 2: Definition of Response Time (TR, TF):

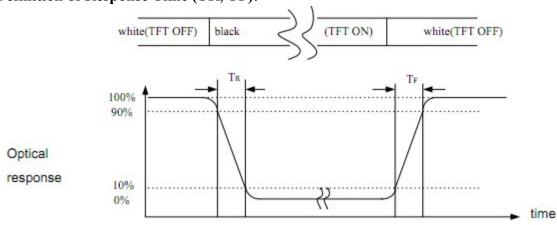


Figure 2

Note 3: Viewing Angle:

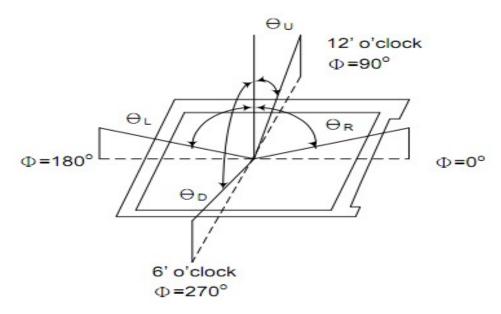


Figure 3

The above "Viewing Angle" is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O'clock. Module maker can increase the "Viewing Angle" by applying Wide View Film.

Note 4: Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.

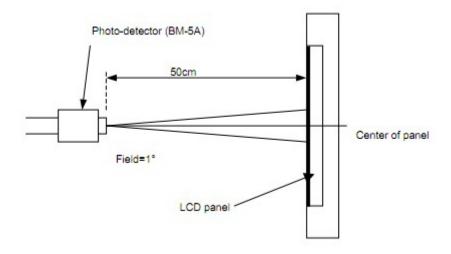


Figure 4

Note 5: Definition of colder chromaticity (CIE61747-1)

Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig.2) Every measuring point is placed at the center of each measuring area.

Luminance Uniformity(U) = Limn/Lmax

L----Active area length W-----Active area width

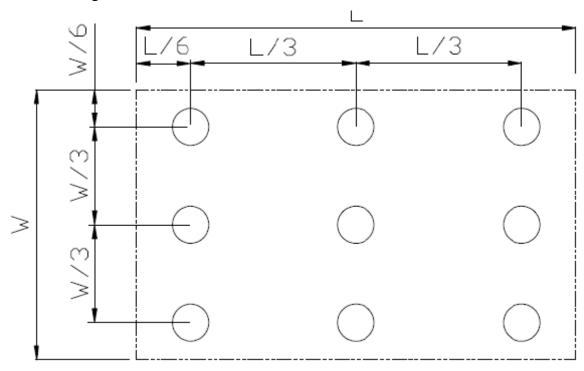


Fig. 2 Definition of uniformity

Lmax: The measured maximum luminance of all measurement position.

Lmin: The measured minimum luminance of all measurement position.

Note 7: Definition of Luminance

Measure the luminance of white state at chanter point.

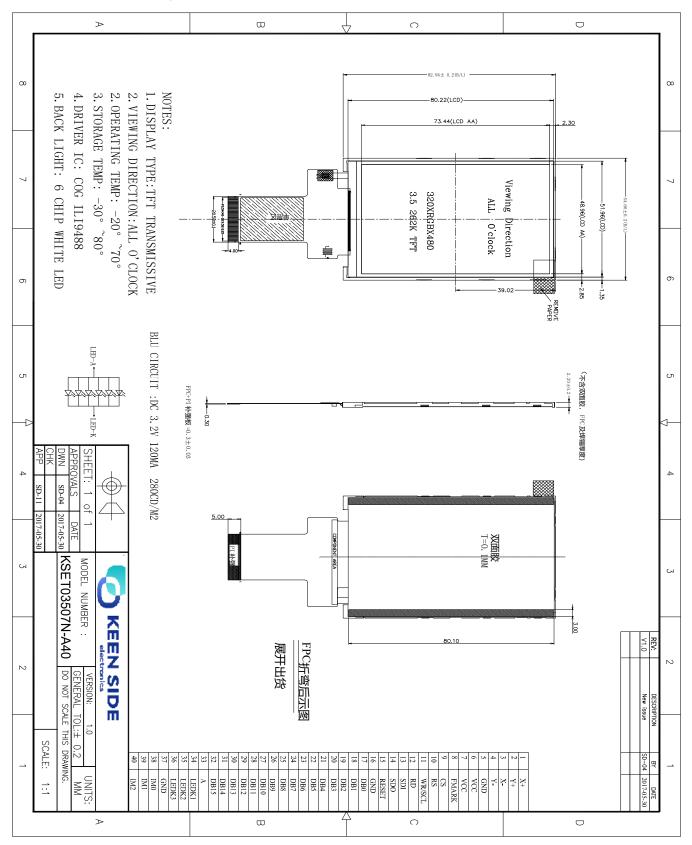
7. Environmental / Reliability Tests

No	Test Item	Condition	Remarks
1	High Temperature Opeartion	Ts=+70°C, 96hrs	Note 1 IEC60068-2-2, GB2423. 2-89
2	Low Temperature Opeartion	Ta= -20°C, 96hrs	Note 2 IEC60068-2-1 GB2423.1-89
3	High Temperature Storage	Ta=+80°C, 96hrs	IEC60068-2-2 GB2423. 2-89
4	Low Temperature Storage	Ta= +70°C, 96hrs	IEC60068-2-1 GB/T2423.1-89
5	High Temperature & Humidity Storage	Ta=+60°C, 90% RH max, 96 hours	IEC60068-2-3 GB/T2423.3-2006
6	Thermal Shock (Non-operation)	-30°C 30 min ~ +80°C 30 min Change time: 5min, 30 Cycle	Start with cold temperature, end with high temperature IEC60068-2-14, GB2423.22-87
7	Electro Static Discharge (Operations)	C=150pF, R=330 Ω , 5 points/panel Air: \pm 8KV, 5 times; Contact: \pm 4KV, 5 times; (Environment: 15°C ~ 35°C, 30% ~ 60%, 86Kpa ~ 106Kpa)	IEC61000-4-2 GB/T17626.2-1998
8	Vibration (Non-operation)	Frequency range: 10~55Hz, Stroke: 1.mm Sweep: 10Hz~55Hz~10Hz 2 hours for each direction of X .Y. Z. (package condition)	IEC60068-2-6 GB/T2423.5-1995
9	Shock (Non-operation)	60G 6ms, \pm X, \pm Y, \pm Z 3 times for each direction	IEC60068-2-27 GB/T2423.5-1998
10	Package Drop Test	Height: 80 cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8-1995

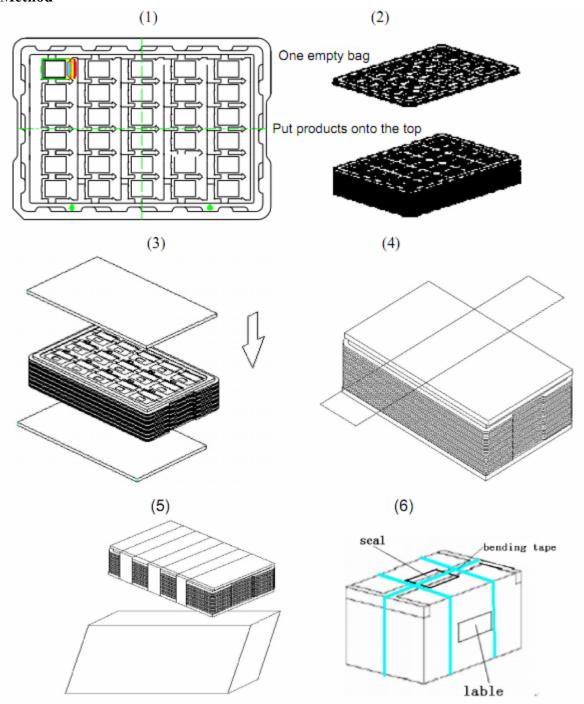
Note: 1. T_S is the temperature of panel's surface.

2. Ta is the ambient temperature of sample.

8. Mechanical Drawing



9. Packing Packing Method



- 1. Put module into tray cavity:
- 2. Tray stacking.
- 3. Put 1 cardboard under the tray stack and 1 cardboard above:
- 4. Fix the cardboard to the tray stack with adhesive tape:
- 5. Put the tray stack into carton.
- 6. Carton sealing with adhesive tape.

10. Precautions for Use of LCD modules

10.1 Handling Precautions

- 10.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents
- 10.1.6. Do not attempt to disassemble the LCD Module.
- 10.1.7. If the logic circuit power is off, do not apply the input signals.
- 10.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- 10.1.8.1. Be sure to ground the body when handling the LCD Modules.
- 10.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.
- 10.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 10.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.